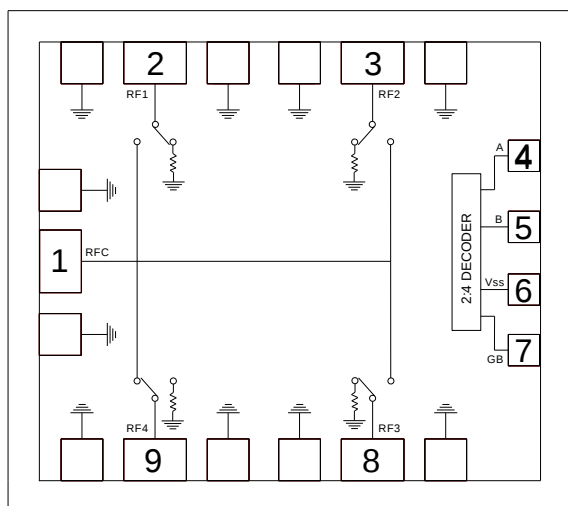


Product Overview

The CMD203 is a broadband MMIC SP4T switch in die form. The CMD203 covers DC to 20 GHz and offers a low insertion loss of 2.4 dB and high isolation of 39 dB at 10 GHz. The switch also includes an on board binary decoder circuit which reduces the number of required logic control lines from four to two. The CMD203 operates using complementary control voltage logic lines of 0/-5 V and consumes little DC current.

Functional Block Diagram



Key Features

- Low Loss Broadband Performance
- High Isolation
- Non-Reflective Design
- Integrated 2:4 TTL Decoder
- Small Die Size

Ordering Information

Part No.	Description
CMD203	50 pcs in gel pack

Electrical Performance ($V_{ctl} = 0/-5\text{ V}$, $V_{ss} = -5\text{ V}$, $T_A = 25^\circ\text{C}$, $F = 10\text{ GHz}$)

Parameter	Min	Typ	Max	Units
Frequency Range		DC - 20		GHz
Insertion Loss		2.4		dB
Isolation		45		dB
Return Loss - On State		9		dB
Return Loss RF1, RF2, RF3, RF4 - Off State		11		dB
Input P1dB		21		dBm
Switching Characteristics				
tRISE, tFALL (10/90% RF)		66		ns
tON, tOFF (50% CTL to 10/90% RF)		81/8		ns

Absolute Maximum Ratings

Parameter	Rating
RF Input Power	+27 dBm
Bias Voltage (V_{SS})	-7V
Control Voltage Range (A, B)	+0.5V to -7.5V
Channel Temperature, T_{ch}	150° C
Operating Temperature	-40 to 85° C
Storage Temperature	-55 to 150° C
Terminated Power Level	531 mW
Thermal Resistance, Q_{JC}	122.23° C/W

Exceeding any one or combination of the maximum ratings may cause permanent damage to the device.

Bias Voltage & Current

V_{SS} Range = -5.0V $\pm$ 10%		
V_{SS} (V)	I_{SS} (Typ) (mA)	I_{SS} (Max) (mA)
-5	4.5	8.0

TTL/CMOS Control Voltages

State	Bias Condition
Low	-1V to 0V @ 0.5 mA Typ
High	-7V to -3V @ 1 uA Typ

Truth Table

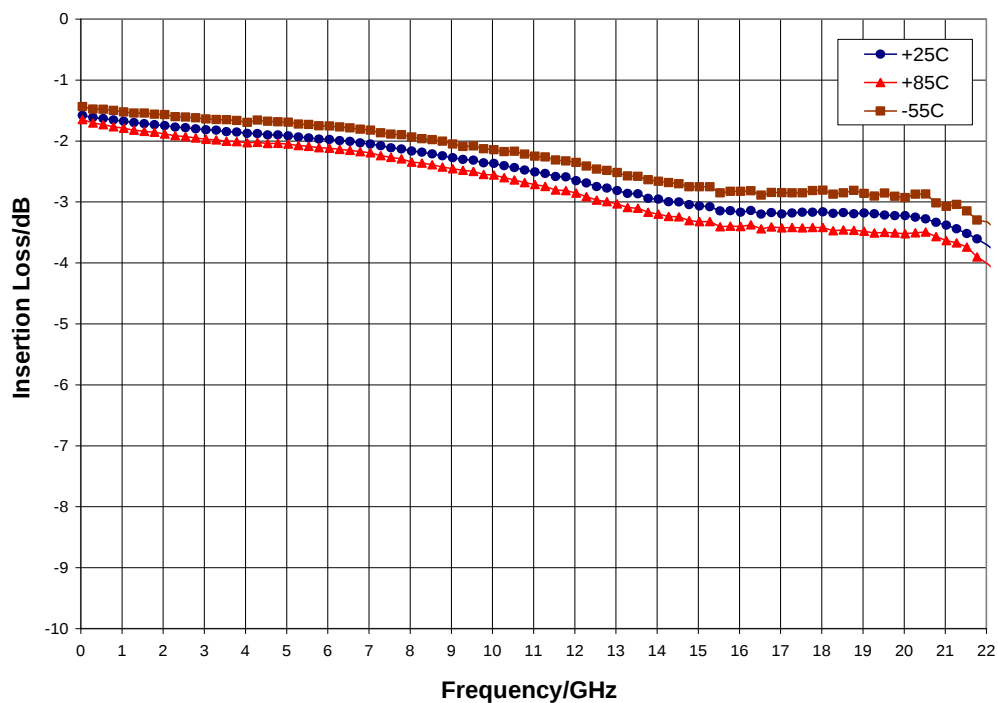
Control Input		Signal Path State
A	B	RFC to:
High	High	RF1
Low	High	RF2
High	Low	RF3
Low	Low	RF4

Electrical Specifications ($V_{ctl} = 0/-5$ V, $V_{SS} = -5$ V $T_A = 25^\circ$ C)

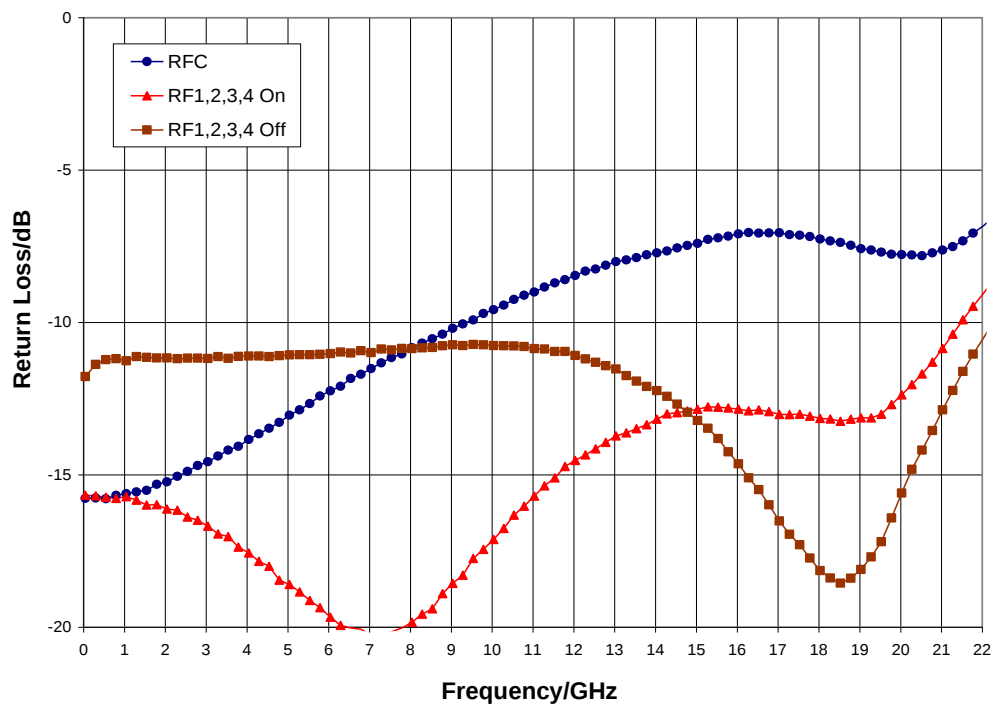
Parameter	Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	Units
Frequency Range		DC - 6			DC - 14			DC - 20		GHz
Insertion Loss		2	2.4		2.9	3.4		3.2	3.6	dB
Isolation	50	60		36	42		35	40		dB
Return Loss - On State		11			8			8		dB
Return Loss - Off State		11			12			15		dB
Input P1dB		19.5			21			22		dBm
Input IP3		28			30			30		dBm
Switching Characteristics										
tRISE, tFALL (10/90% RF)		66			66			66		ns
tON, tOFF (50% CTL to 10/90% RF)		81/8			81/8			81/8		ns

Typical Performance

Insertion Loss vs. Temperature

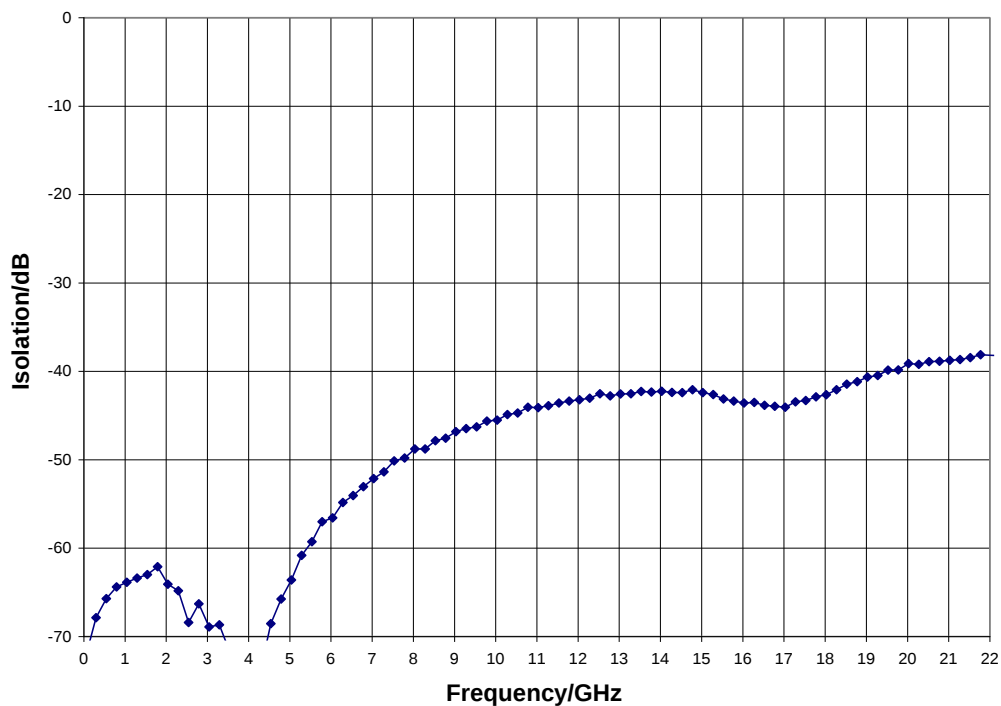


Return Loss

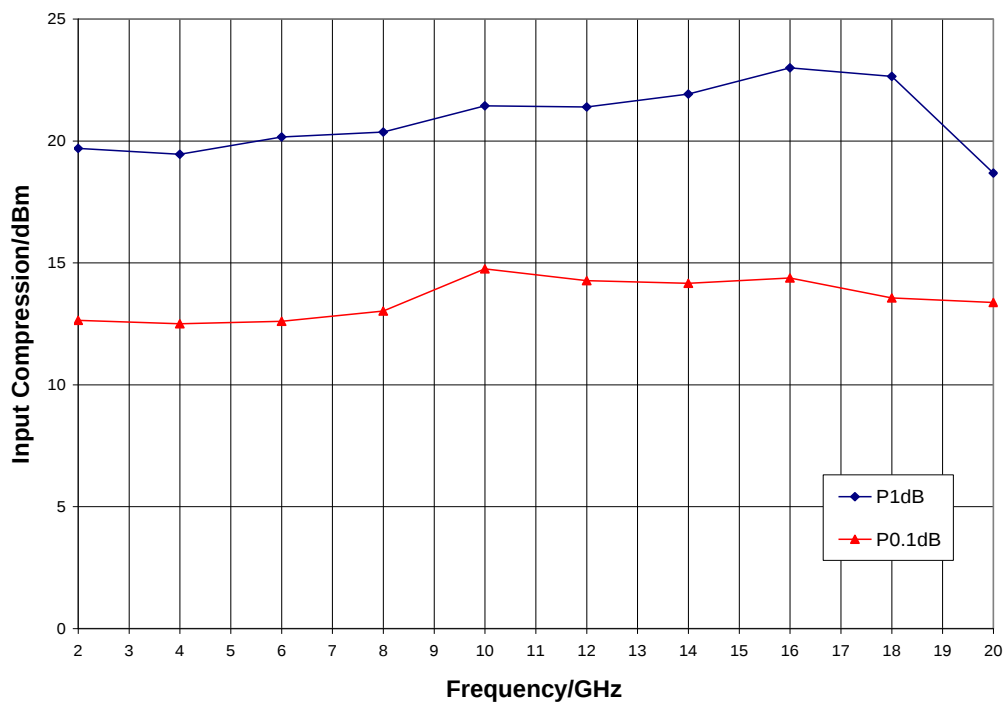


Typical Performance

Typical Isolation Between Ports RFC and RF1/RF2/RF3/RF4

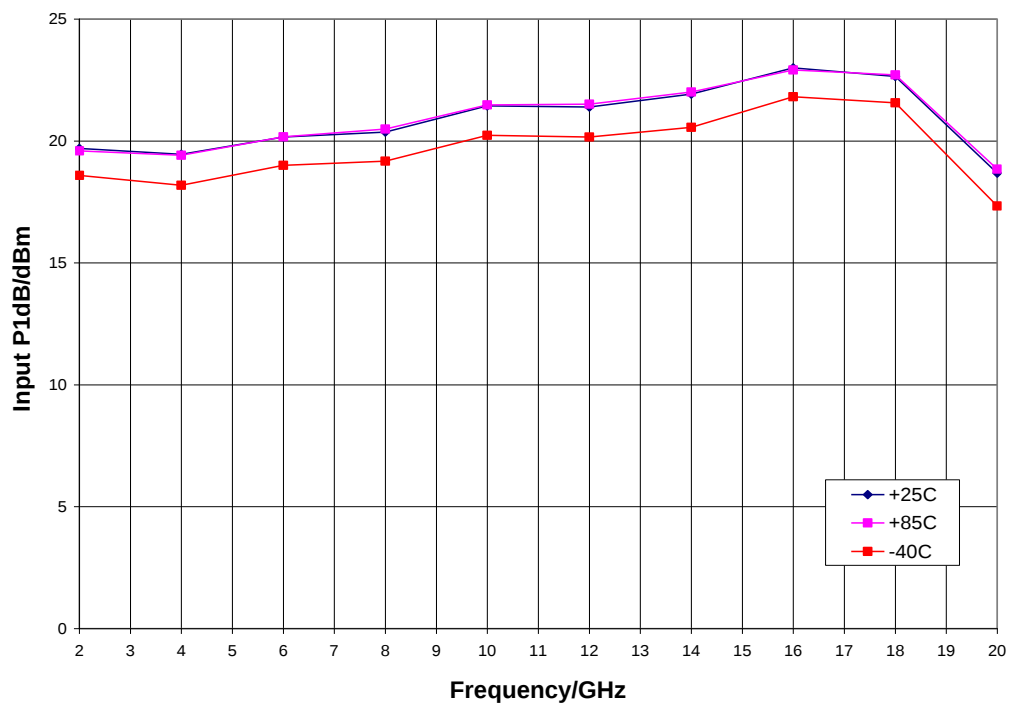


Input P1dB and P0.1dB Compression Point

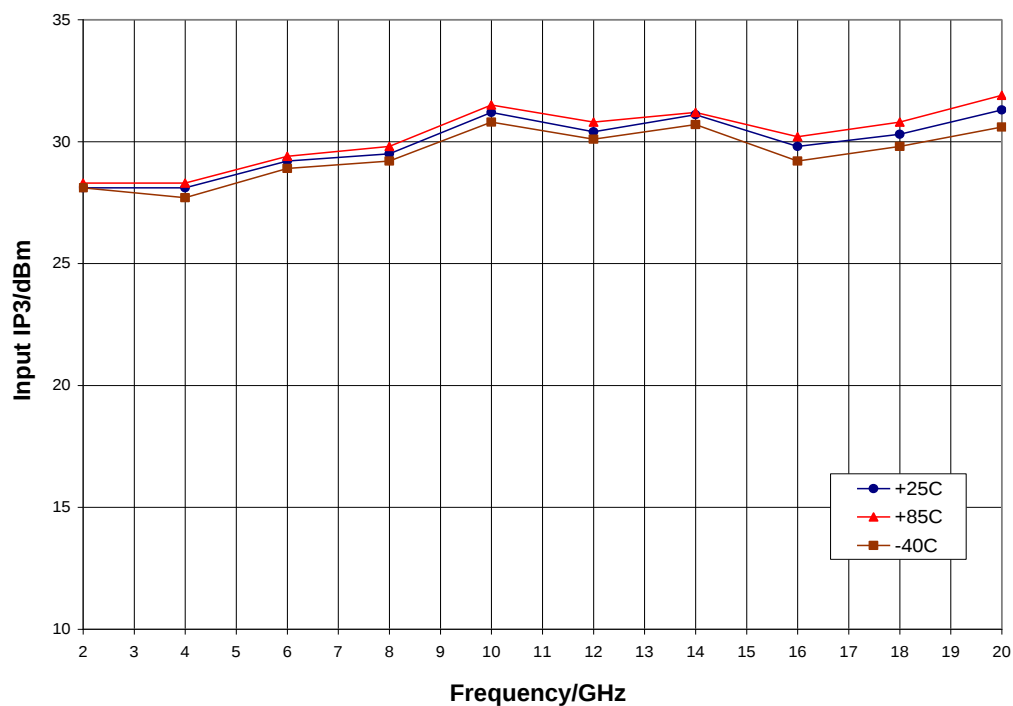


Typical Performance

Input P1dB vs. Temperature

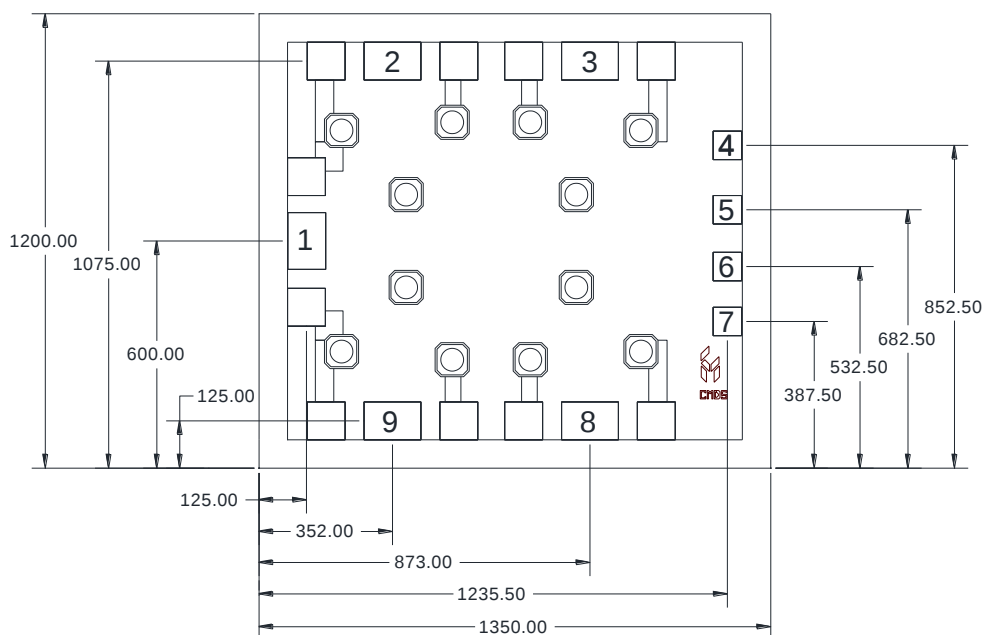


Input Third Order Intercept Point vs. Temperature



Mechanical Information

Die Outline (all dimensions in microns)

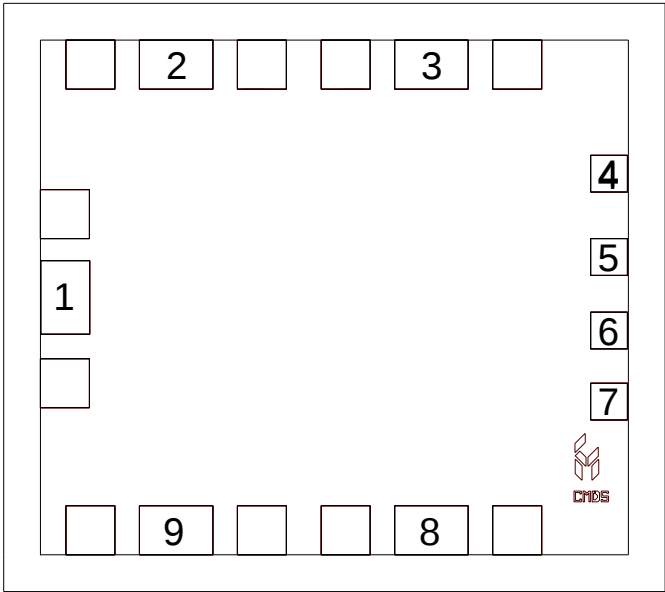


Notes:

1. No connection required for unlabeled pads
2. Backside is RF and DC ground
3. Backside and bond pad metal: Gold
4. Die is 85 microns thick
5. DC bond pads (4, 5, 6, 7) are 75 x 75 microns
6. RF bond pads (1, 2, 3, 8, 9) are 100 x 150 microns

Pin Description

Pad Diagram



Functional Description

Pin	Function	Description	Schematic
1, 2, 3, 8, 9	RFC, RF1, RF2, RF3, RF4	These pins are DC coupled and matched to 50 ohm Blocking capacitors are required if RF line potential is not equal to 0 V	
4	CTLA	See truth table and control voltage table	
5	CTLB	See truth table and control voltage table	
6	Vss	Power supply voltage	
7	GB	Connect to DC ground	
Backside	Ground	Connect to RF / DC ground	

Applications Information

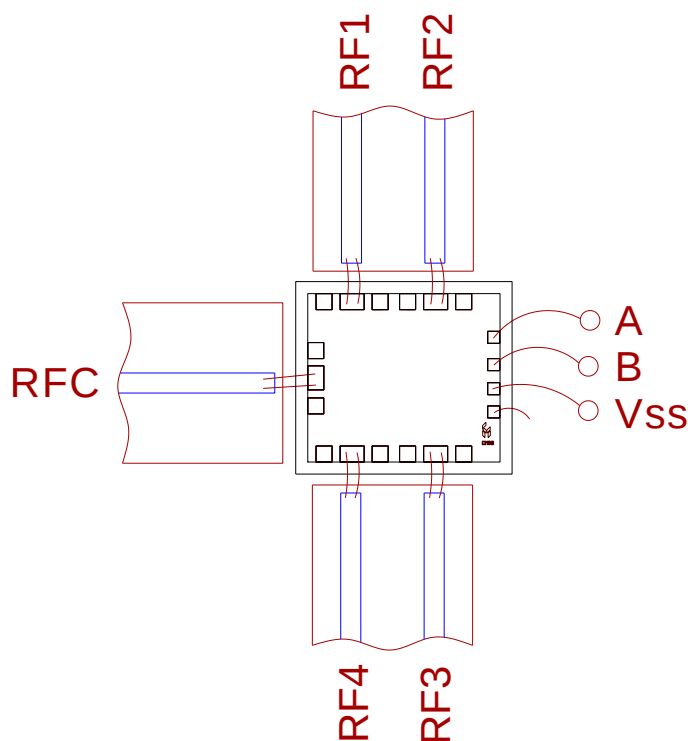
Assembly Guidelines

The backside of the CMD203 is RF ground. Die attach should be accomplished with electrically and thermally conductive epoxy only. Eutectic attach is not recommended. Standard assembly procedures should be followed for high frequency devices. The top surface of the semiconductor should be made planar to the adjacent RF transmission lines, and the RF decoupling capacitors placed in close proximity to the DC connections on chip.

RF connections should be made as short as possible to reduce the inductive effect of the bond wire. Use of a 0.8 mil thermosonic wedge bonding is highly recommended as the loop height will be minimized. The RF inputs and outputs require a double bond wire as shown.

The semiconductor is 85 μm thick and should be handled by the sides of the die or with a custom collet. Do not make contact directly with the die surface as this will damage the monolithic circuitry. Handle with care.

Assembly Diagram



Handling Precautions

Parameter	Rating	Standard
ESD – Human Body Model (HBM)	Class 1A	ESDA / JEDEC JS-001-2012



Caution!
ESD-Sensitive Device

RoHS Compliance

This part is compliant with 2011/65/EU RoHS directive (Restrictions on the Use of Certain Hazardous Substances in Electrical and Electronic Equipment) as amended by Directive 2015/863/EU.

This product also has the following attributes:

- Lead Free
- Antimony Free
- TBBP-A (C₁₅H₁₂Br₄O₂) Free
- SVHC Free
- PFOS Free
- Halogen Free



Contact Information

For the latest specifications, additional product information, worldwide sales and distribution locations:

Web: www.qorvo.com

Tel: 1-844-890-8163

Email: customer.support@qorvo.com

Important Notice

The information contained in this Data Sheet and any associated documents ("Data Sheet Information") is believed to be reliable; however, Qorvo makes no warranties regarding the Data Sheet Information and assumes no responsibility or liability whatsoever for the use of said information. All Data Sheet Information is subject to change without notice. Customers should obtain and verify the latest relevant Data Sheet Information before placing orders for Qorvo® products. Data Sheet Information or the use thereof does not grant, explicitly, implicitly or otherwise any rights or licenses to any third party with respect to patents or any other intellectual property whether with regard to such Data Sheet Information itself or anything described by such information.

DATA SHEET INFORMATION DOES NOT CONSTITUTE A WARRANTY WITH RESPECT TO THE PRODUCTS DESCRIBED HEREIN, AND QORVO HEREBY DISCLAIMS ANY AND ALL WARRANTIES WITH RESPECT TO SUCH PRODUCTS WHETHER EXPRESS OR IMPLIED BY LAW, COURSE OF DEALING, COURSE OF PERFORMANCE, USAGE OF TRADE OR OTHERWISE, INCLUDING THE IMPLIED WARRANTIES OF MERCHANTABILITY AND FITNESS FOR A PARTICULAR PURPOSE. Without limiting the generality of the foregoing, Qorvo® products are not warranted or authorized for use as critical components in medical, life-saving, or life-sustaining applications, or other applications where a failure would reasonably be expected to cause severe personal injury or death. Applications described in the Data Sheet Information are for illustrative purposes only. Customers are responsible for validating that a particular product described in the Data Sheet Information is suitable for use in a particular application.

© 2020 Qorvo US, Inc. All rights reserved. This document is subject to copyright laws in various jurisdictions worldwide and may not be reproduced or distributed, in whole or in part, without the express written consent of Qorvo US, Inc. | QORVO® is a registered trademark of Qorvo US, Inc.

Mouser Electronics

Authorized Distributor

Click to View Pricing, Inventory, Delivery & Lifecycle Information:

[Qorvo:](#)
[CMD203](#)